

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (Canceled)

9. (Currently Amended) A semiconductor device test probe having a tip portion for being urged against a plurality of electrode pads of an integrated semiconductor device to establish electrical contacts between the tip portion and the electrode pads for testing an operation of the semiconductor;

said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature r expressed by $10\text{ }\mu\text{m} \leq r \leq 20\text{ }\mu\text{m}$.

10. (New): A semiconductor device test probe having a tip portion for being urged against a plurality of electrode pads of an integrated semiconductor device to establish electrical contacts between the tip portion and the electrode pads for testing an operation of the semiconductor;

said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature r expressed by $10\text{ }\mu\text{m} \leq r \leq 20\text{ }\mu\text{m}$, and said tip portion generating a shear deformation on the electrode pads.